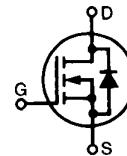


HiPerFET™ Power MOSFETs

IXFH 13N50 IXFM 13N50

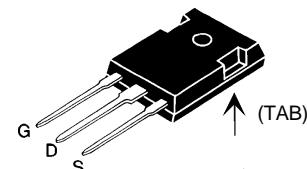
N-Channel Enhancement Mode
High dv/dt, Low t_{rr} , HDMOS™ Family

V_{DSS} = 500 V
 I_D (cont) = 13 A
 $R_{DS(on)}$ = 0.4 Ω
 t_{rr} ≤ 250 ns

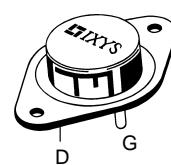


Symbol	Test Conditions	Maximum Ratings		
V_{DSS}	T_J = 25°C to 150°C	500	V	
V_{DGR}	T_J = 25°C to 150°C; $R_{GS} = 1 \text{ M}\Omega$	500	V	
V_{GS}	Continuous	±20	V	
V_{GSM}	Transient	±30	V	
I_{D25}	$T_C = 25^\circ\text{C}$	13	A	
I_{DM}	$T_C = 25^\circ\text{C}$, pulse width limited by T_{JM}	52	A	
I_{AR}	$T_C = 25^\circ\text{C}$	13	A	
E_{AR}	$T_C = 25^\circ\text{C}$	18	mJ	
dv/dt	$I_S \leq I_{DM}$, $dv/dt \leq 100 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 2 \Omega$	5	V/ns	
P_D	$T_C = 25^\circ\text{C}$	180	W	
T_J		-55 ... +150	°C	
T_{JM}		150	°C	
T_{stg}		-55 ... +150	°C	
T_L	1.6 mm (0.062 in.) from case for 10 s	300	°C	
M_d	Mounting torque	1.13/10	Nm/lb.in.	
Weight		TO-204 = 18 g, TO-247 = 6 g		

TO-247 AD (IXFH)



TO-204 AA (IXFM)



G = Gate,
S = Source,
TAB = Drain

Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
V_{DSS}	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	500		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 2.5 \text{ mA}$	2	4	V
I_{GSS}	$V_{GS} = \pm 20 \text{ V}_{DC}$, $V_{DS} = 0$		±100	nA
I_{DSS}	$V_{DS} = 0.8 \cdot V_{DSS}$ $V_{GS} = 0 \text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	200	μA 1 mA
$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$, $I_D = 0.5 \cdot I_{D25}$ Pulse test, $t \leq 300 \mu\text{s}$, duty cycle d ≤ 2 %		0.4	Ω

Features

- International standard packages
- Low $R_{DS(on)}$ HDMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
 - easy to drive and to protect
- Fast intrinsic Rectifier

Applications

- DC-DC converters
- Uninterruptible Power Supplies (UPS)
- Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- Temperature and lighting controls
- Low voltage relays

Advantages

- Easy to mount with 1 screw (TO-247) (isolated mounting screw hole)
- Space savings
- High power density

IXYS reserves the right to change limits, test conditions, and dimensions.

91524D (10/95)

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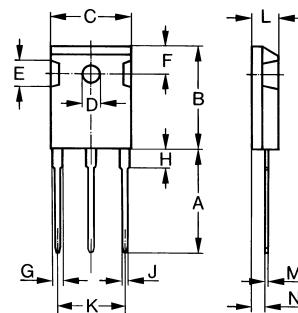
Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
g_{fs}	$V_{DS} = 10 \text{ V}; I_D = 0.5 I_{D25}$, pulse test	7.5	9.0	S
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	2800	pF	
		300	pF	
		70	pF	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}, R_G = 4.7 \Omega$ (External)	18	30	ns
		27	40	ns
		76	100	ns
		32	60	ns
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 \cdot I_{D25}$	110	120	nC
		15	25	nC
		40	50	nC
R_{thJC}			0.7	K/W
R_{thCK}			0.25	K/W

Source-Drain Diode

Characteristic Values
($T_J = 25^\circ\text{C}$, unless otherwise specified)

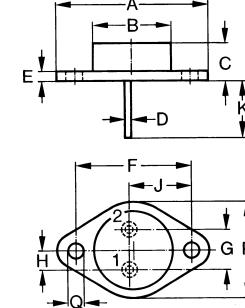
Symbol	Test Conditions	Characteristic Values		
		($T_J = 25^\circ\text{C}$, unless otherwise specified)	min.	typ.
I_s	$V_{GS} = 0 \text{ V}$		13	A
I_{SM}	Repetitive; pulse width limited by T_{JM}		52	A
V_{SD}	$I_F = I_s, V_{GS} = 0 \text{ V}$, Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2\%$		1.5	V
t_{rr} Q_{RM} I_{RM}	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$ $I_F = I_s$ $-di/dt = 100 \text{ A}/\mu\text{s}$, $V_R = 100 \text{ V}$	250	ns	
		350	ns	
		0.6	μC	
		1.25	μC	
		9	A	
		15	A	

TO-247 AD (IXFH) Outline



Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	19.81	20.32	0.780	0.800
B	20.80	21.46	0.819	0.845
C	15.75	16.26	0.610	0.640
D	3.55	3.65	0.140	0.144
E	4.32	5.49	0.170	0.216
F	5.4	6.2	0.212	0.244
G	1.65	2.13	0.065	0.084
H	-	4.5	-	0.177
J	1.0	1.4	0.040	0.055
K	10.8	11.0	0.426	0.433
L	4.7	5.3	0.185	0.209
M	0.4	0.8	0.016	0.031
N	1.5	2.49	0.087	0.102

TO-204 AA (IXFM) Outline



Dim.	Millimeter Min.	Max.	Inches Min.	Max.
A	38.61	39.12	1.520	1.540
B	19.43	19.94	-	0.785
C	6.40	9.14	0.252	0.360
D	0.97	1.09	0.038	0.043
E	1.53	2.92	0.060	0.115
F	30.15	BSC	1.187	BSC
G	10.67	11.17	0.420	0.440
H	5.21	5.71	0.205	0.225
J	16.64	17.14	0.655	0.675
K	11.18	12.19	0.440	0.480
Q	3.84	4.19	0.151	0.165
R	25.16	25.90	0.991	1.020

Fig. 1 Output Characteristics

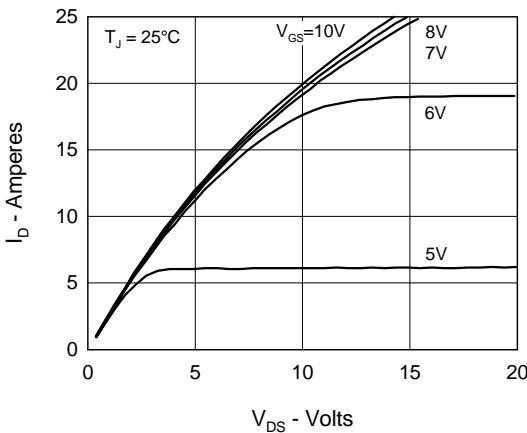


Fig. 3 $R_{DS(on)}$ vs. Drain Current

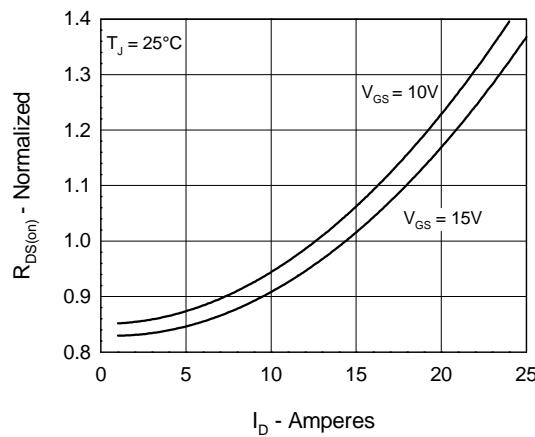


Fig. 5 Drain Current vs. Case Temperature

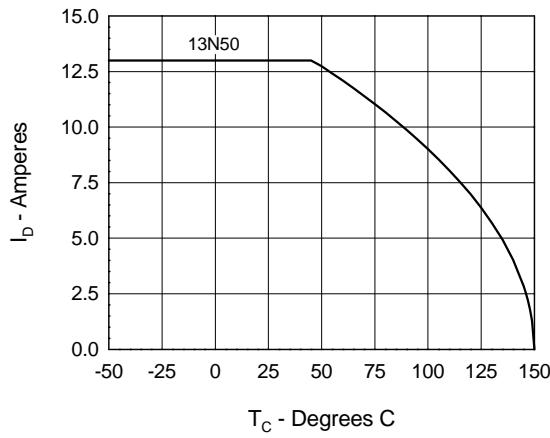


Fig. 2 Input Admittance

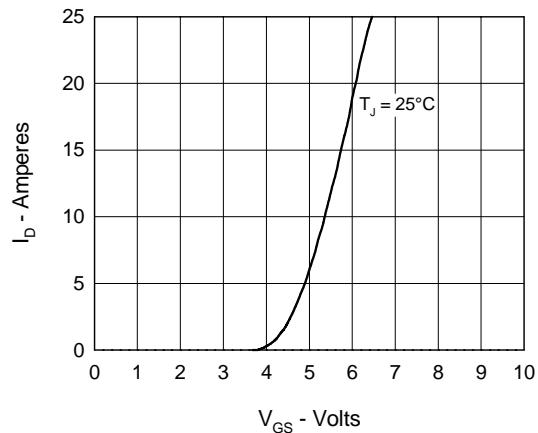


Fig. 4 Temperature Dependence of Drain to Source Resistance

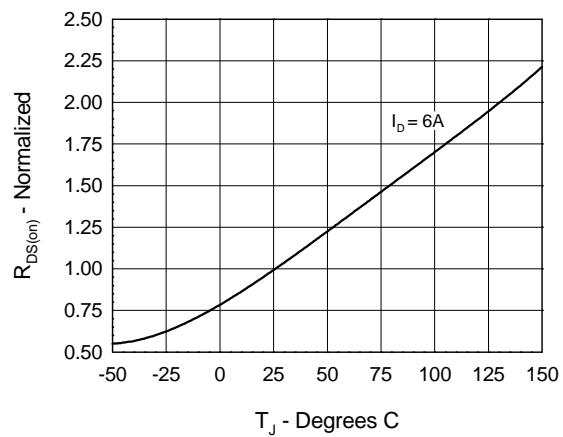


Fig. 6 Temperature Dependence of Breakdown and Threshold Voltage

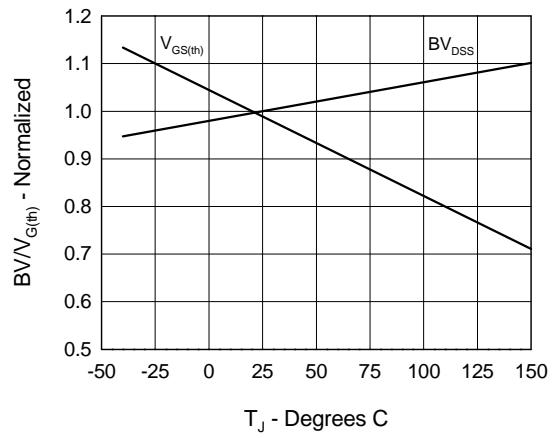


Fig.7 Gate Charge Characteristic Curve

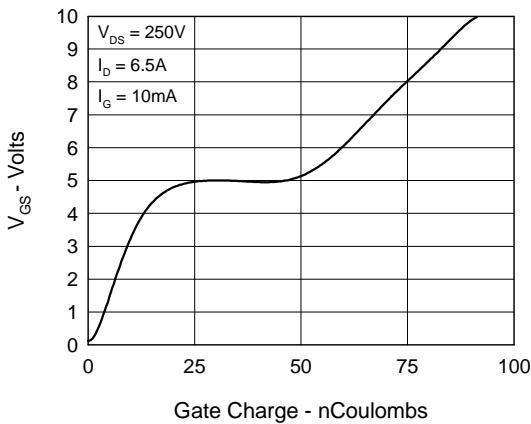


Fig.9 Capacitance Curves

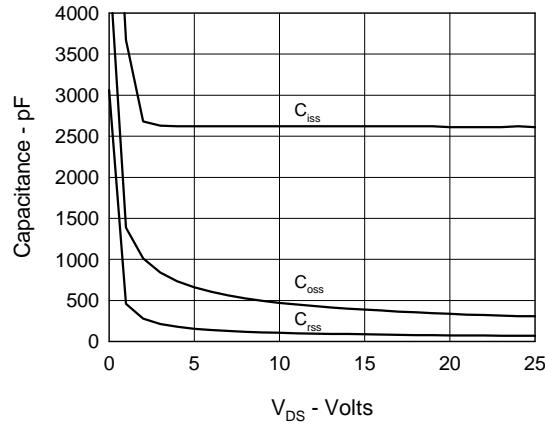


Fig.8 Forward Bias Safe Operating Area

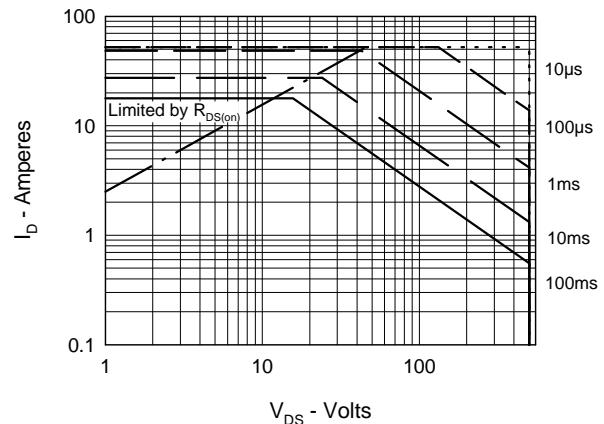


Fig.10 Source Current vs. Source to Drain Voltage

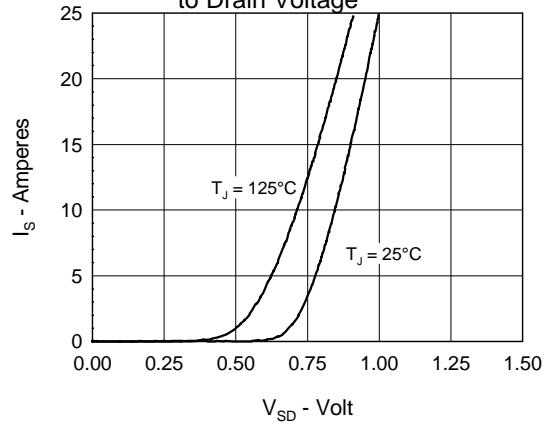


Fig.11 Transient Thermal Impedance

